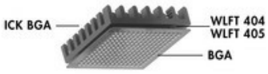
Data sheet Product ICK BGA 10 x 10 x 10



Heatsinks and active heatsinks for processors > Heatsinks for BGAs
10 x 10 x 10 mm, for IC design BGA and others

Features

way of fixation	therm. conductive foil therm. cond. adhesive
socket	universal
suitable for processor type	universal
width B	10 mm
height	10 mm
plate thickness	1.8 mm
length	10 mm
thermal resistance R_{th}	28.5 - 9.1 K/W
dissipation loss P_v	1.9 W
surface	black anodised

Technical Drawing